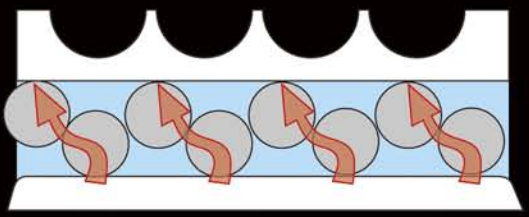
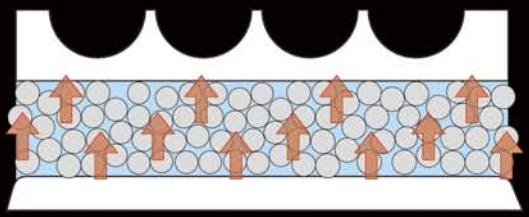
PK-3

Like two hot lovers, a heatsink and the processor want to make full contact. But microscopic imperfections in their craftsmanship create small gap for air. These gaps act as thermal insulators, inhibiting the transfer of thermal energy from your components.



OTHERS



PK-3

PK-3 thermal compound is made up of specially designed nano particles, engineered to correct these imperfections. The nano particles work by filling in the small air gaps and allowing for peak transfer of heat away from your components.

Features:

- High Thermal Conductivity
- Low Thermal Resistance
- Long-Term Stability
- Low Dry-Out
- Non-Corrosive
- Electrically Non-Conductive
- No "burn-in" time required

Material Specification:

Substance name content

- Al 70~88 (wt%)
- ZnO 18~34 (wt%)
- Oil 8~12 (wt%)
- Antioxidant 0.5~2 (wt%)

Specification:

- Specific Gravity: 2.7g/cm³
- Adhesiveness: 330000 Cps
- Thermal Conductivity: 11.2 W/m-℃
- Thermal Impedance: 0.013 ℃-in²/W